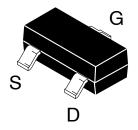


Switch, N-Chanel

Features

- This Device is Designed for Low Level Analog Switching Applications, Sample and Hold Circuits and Chopper Stabilized Amplifiers.
- Sourced from Process 51.
- This is a Pb-Free and a Halide Free Device



SOT-23

ABSOLUTE MAXIMUM RATINGS (Note 1), (Note 2)($T_A = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DG}	Drain-Gate Voltage	40	V
V _{GS}	Gate-Source Voltage	-40	V
I _{GF}	Forward Gate Current	50	mA
T _J , T _{STG}	Γ _J , T _{STG} Operating and Storage Junction Temperature Range		°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Symbol	Characteristic	Max	Unit	
P_{D}	Total Device Dissipation	350	mW	
	Derate above 25°C	2.8	mW/°C	
RθJA	Thermal Resistance, Junction to Ambient (Note 3)	357	°C/W	

These ratings are based on a maximum junction temperature of 150°C.



ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

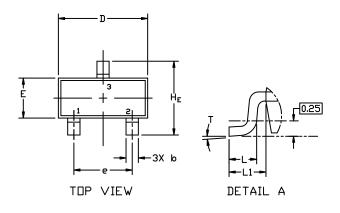
Symbol	Parameter	Test Conditions		Max	Unit
FF CHARAC	TERISTICS	•	•		
V _{(BR)GSS}	Gate-Source Breakdown Voltage	I _G = 1 μA, V _{DS} = 0	-40	_	V
V _{GS} (off)	Gate-Source Cut-Off Voltage	V _{DS} = 20 V, I _D = 1 nA	-1.0	-5.0	V
I _{DGO}	Drain-Gate Leakage Current	V _{DG} = 20 V, I _S = 0 V _{DG} = 20 V, I _S = 0, T _A = 150°C -		-200 -400	pA nA
I _D (off)	Drain Cutoff Leakage Current	V _{DS} = 20 V, V _{GS} = -6 V V _{DS} = 20 V, V _{GS} = -6 V, T _A = 150°C	_ _	200 400	pA nA
N CHARACT	ERISTICS	•	•		
I _{DSS}	Zero-Gate Voltage Drain Current (Note 4)	V _{DS} = 20 V, I _{GS} = 0	8	_	mA
V _{DS} (on)	Drain-Source On Voltage	I _D = 2.5 mA, V _{GS} = 0	-	0.2	V
r _{DS} (on)	Drain-Source On Resistance	I _D = 1 mA, V _{GS} = 0	-	80	Ω
MALL SIGNA	AL CHARACTERISTICS				
r _{DS} (on)	Drain-Source On Resistance	V _{DS} = V _{GS} = 0, f = 1 kHz	_	80	Ω
C _{iss}	Input Capacitance	V _{DS} = 20 V, V _{GS} = 0 V, f = 1.0 MHz	-	16	pF
C _{rss}	Reverse Transfer Capacitance	V _{DS} = -20 V, f = 1.0 MHz	-	5	pF
WITCHING C	HARACTERISTICS	•	-	-	-
t _{On}	Turn-On Time	I _{D(on)} = 3.0 mA	_	60	ns
t _{Off}	Turn-Off Time	V _{GS(off)} = 3.0 V	_	80	ns

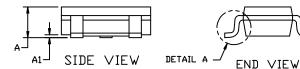
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{4.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 1%.



SOT-23 (TO-236)

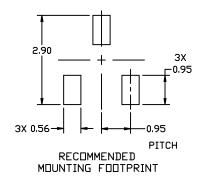




NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
Ε	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0*		10 *	0*		10°



CCS Semiconductor and CSCM are trademarks of Semiconductor Components Industries, CCS Semiconductor reserves the right to make changes without further notice to any products herein. CCS Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does CCS Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. CCS Semiconductor does not convey any license under its patent rights nor the rights of others.